

# Deptrum® Stellar 400 Specifications

V4.0 - 8/2/2022



## INTRODUCTION

Deptrum® Stellar 400 is one of Deptrum's depth camera series that utilize Time-of-Flight (ToF) technology to obtain 3-dimensional information of target objects or space. It combines the depth data captured together with RGB image information, and thus bringing consumers with effective 3D sensing capabilities.

Via USB2.0 interface, Stellar 400 is powered and outputs ToF depth data and RGB image at maximum frame rate of 30fps . With the unique optics, electronics and high-precision algorithm to calculate the depth information, the depth measurement precision can reach millimeter level.

## SYSTEM REQUIREMENTS

- Operating Systems:  
Windows /Linux/Android/ROS

## FEATURES

- Millimeter level precision
- Depth range of 0.2m ~ 5m
- Temperature drift compensation to ensure high accuracy as well as quality of depth image in various temperature conditions
- Simultaneous output of RGB, IR, and depth images
- Support alignment of RGB, IR, and depth images
- Adjustable detection range and frame rate

## APPLICABILITIES

- Robot Navigation
- Volume&Dimensions Measurement
- Liveness Detection
- Somatosensory Interaction
- Head Counting
- 3D Modeling

## Specifications

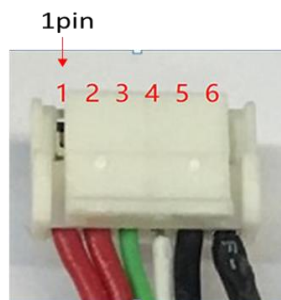
Stellar 400		
Camera module	Dimensions	79mm x 35mm x 15.7mm
	Laser Wavelength	940nm
	Interface	USB 2.0 Wafer
	Depth Accuracy	5mm@1m
	Depth Range	0.2~5m
	Operating Temperature	-10℃~50℃
	Operating Humidity	0%~95%
	Power Supply	Avg:5V±10%/1A(Peak>5V/2A)
	Power Consumption	Avg:<3.6W
	ESD	Contact:±4KV, Air:±8KV
	Laser Safety	Class 1
Frame Data	Data format	RGB/IR/Depth: JPEG/Raw 16/Raw 8
	DepthResolution/Frame rate/FOV	640x480/25fps/64°(H)x51°(V)
	RGB Resolution/Frame rate/FOV	640x480/25fps/76°(H)x61°(V)
	IR Resolution/Frame rate/FOV	640x480/25fps/64°(H)x51°(V)
Synchronous Output Mode	Spontaneous Output	Maximum delay between RGB/IR/Depth:40ms
	Pixel-level alignment	±5 pixel
Operating Systems	System Compatibility	Windows / Linux / Android / ROS

## Figure of Module



Module	Number
USB Wafer	1
TOF Camera	2
Vcsl	3
RGB Camera	4

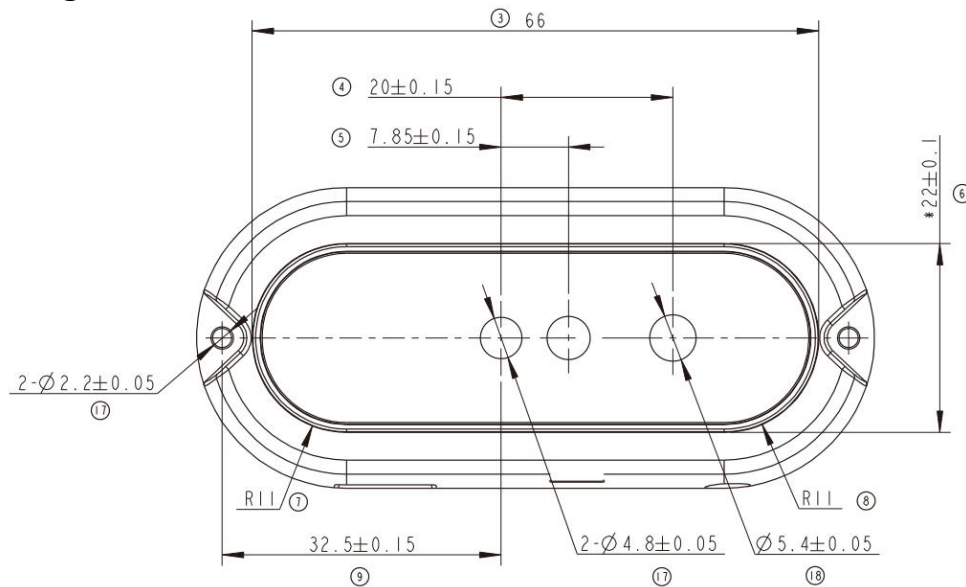
## Interface Definition



USB 2.0 Wafer

1,2、VBUS	3、D+	4、D-	5,6、GND
----------	------	------	---------

## Structure Diagram



## SECONDARY DEVELOPMENT

Customers are able to proceed to application development by using Deptrum Stellar SDK. It supports Windows/Linux/Android/ROS platform and x86\_64 and ARMv7/ARMv8 architecture, and has been optimized with several specific capabilities on the embedded architecture. Please refer to the SDK guidance manual for more details.

## DISCLAIMER

The product specifications and other relevant information provided herein are for reference purposes only, and are subject to replacement by updated product information. It is your responsibility to ensure conventional technical standards are followed during operation of the product. Deptrum disclaims warranties or representations of any kind, expressed or implied, oral or in written, required by law or in any other forms, including without limitation, the warranties of conditions, performance, quality, efficiency, merchantability, or fitness for a particular purpose. Nor does Deptrum assume any liability of the information contained herein or whatsoever arising out of the application or use of that information. Without prior written approval from Deptrum, its products shall not be used as a mission-critical component in a life-support system of any party. Under the protection of Deptrum's intellectual property rights, no license is granted or transferred in any form.

## **SUPPORT**

Please use contact details as follow for support:

- Website: Please visit [www.deptrum.com](http://www.deptrum.com) to acquire guidance documents and online support
- Email: Please raise your enquiries via email to [support@deptrum.com](mailto:support@deptrum.com)
- FAE: Please contact our sales team for further support from FAE staff

## **PRECAUTIONS**

- Please avoid placing the product near any heat source.
- Please do not drop or pound on the product to avoid any damage to the internal components or the deterioration of the measurement accuracy. Improper operations may also cause damage of the internal parts.
- Please do not attempt to open or alter any portion of this device to avoid any damage to the module or possible deterioration of the measurement accuracy.
- It is normal that the module housing temperature rises after being used for a period of time. Heat dissipation measures can be taken at the back of the module housing.
- Please don't keep your eyes too close to the operating product(<10cm) for laser safety.